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Part Number: **0676431910**
Status: **Active**
Description: Universal Serial Bus (USB) Shielded I/O Receptacle, Right Angle, Type A, White Polyester, Gold (Au) Flash Plating, PCB Thickness 1.60mm (.063"), without Upper Flange, Lead Free

Documents:

[3D Model](#) [Product Specification PS-67643-002 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	I/O Connectors
Series	67643
Application	Wire-to-Board
Comments	Without Upper Flange Not for IR Reflow Process
Component Type	Receptacle
Product Name	USB
Type	A

Physical

Boot Color	N/A
Circuits (Loaded)	4
Circuits (maximum)	4
Gender	Receptacle
Keying to Mating Part	Yes
Lock to Mating Part	Yes
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Number of Rows	1
Orientation	Right Angle
PC Tail Length (in)	0.102 In
PC Tail Length (mm)	2.60 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tray
Panel Mount	Yes
Pitch - Mating Interface (in)	0.079 In, 0.098 In
Pitch - Mating Interface (mm)	2.00 mm, 2.50 mm
Pitch - Term. Interface (in)	0.079 In, 0.098 In
Pitch - Term. Interface (mm)	2.00 mm, 2.50 mm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	1
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Through Hole
Waterproof / Dustproof	No

Electrical

Current - Maximum per Contact	1.5A
Shield Type	Full Shield
Shielded	Yes
Voltage - Maximum	30V DC

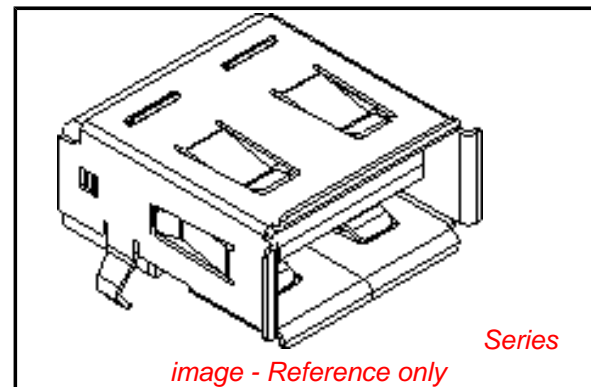


image - Reference only

EU RoHS

ELV and RoHS Compliant
REACH SVHC
 Not Reviewed
Halogen-Free Status

China RoHS



Not Halogen-Free

Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

67643Series

Mates With

USB Type A Plug

Solder Process Data

Lead-free Process Capability
Process Temperature max. C

Wave Capable (TH only)
260

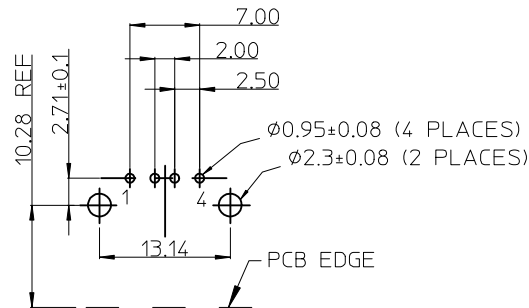
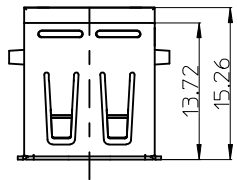
Material Info**Reference - Drawing Numbers**

Product Specification
Sales Drawing

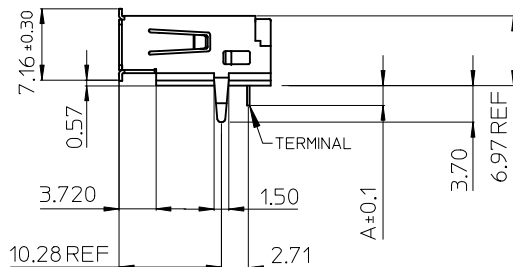
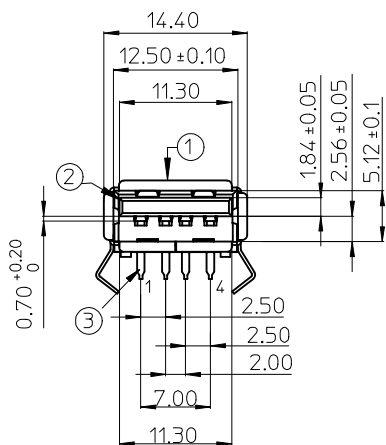
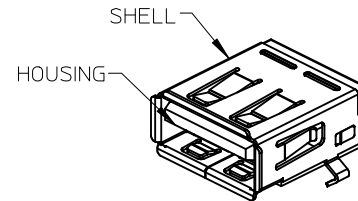
PS-67643-002
SD-67643-003

This document was generated on 04/01/2010

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PCB LAYOUT (TOP VIEW)



NOTES:

1. MATERIAL:

- ① METAL SHELL: COPPER ALLOY.
- ② HOUSING: SEE CHART, 30% GLASS FIBER FILLED, UL94-V0.
- ③ TERMINAL: PHOSPHOR BRONZE

2. TERMINAL:

- CONTACT AREA: (a) GOLD FLASH.
- (b) GOLD (Au), THICKNESS=30 MICROINCH MINIMUM.
- SOLDER TAIL: TIN PLATED, THICKNESS=75 MICROINCH MINIMUM.
- UNDER PLATED: NICKEL (Ni), THICKNESS=50 MICROINCH MINIMUM.
- METAL SHELL: SEE CHART.

3. RECOMMENDED PCB THICKNESS: SEE CHART

4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002

FOR NON IR REFER TO PS-67643-003

5. TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.

6. TEST SUMMARY: FOR IR REFER TO TS-67643-002

FOR NON IR REFER TO TS-67643-003

7. PACKAGE: REFER TO PK-67643-002

8. LEAD FREE AND ROHS COMPLIANT PRODUCT

REVISED EC NO: D DRAWN: YPWU CHKD: APPR:	DESCRIPTION 2009/08/28	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		$\nabla=0$ $\sphericalangle=0$	mm	INCH	DRAWN BY IVY-LIN	DATE 2005/03/31	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)			
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± ---	ANGULAR ± 3 °		CHECKED BY ALL IN	DATE 2005/03/31				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 2		APPROVED BY WWSCHANG	DATE 2005/03/31	MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-67643-003		SHEET NO. 1 OF 2	

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P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK	
67643-0910	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR	
67643-1910	POLYESTER	WHITE			REFLOW PROCESS	
67643-2910	HIGH TEMPERATURE NYLON	BLACK			FOR IR	
67643-3910	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS	
67643-0911	POLYESTER	BLACK	GOLD PLATING 30 MICROINCH		NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS=80 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni).	NON IR
67643-1911	POLYESTER	WHITE				REFLOW PROCESS
67643-2911	HIGH TEMPERATURE NYLON	BLACK				FOR IR
67643-3911	HIGH TEMPERATURE NYLON	WHITE				REFLOW PROCESS
PCB THICKNESS		1.60±0.05				
DIMENSION "A"		2.60				

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P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK	
67643-0930	HIGH TEMPERATURE NYLON	BLACK	GOLD FLASH	FOR IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR	
67643-1930	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS	
67643-0931	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 30 MICROINCH			
67643-1931	HIGH TEMPERATURE NYLON	WHITE				
PCB THICKNESS		1.20±0.05				
DIMENSION "A"		2.00				

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REVISED ECT NO: D DRWN: YPWU CHKD: APPR:	2009/08/28	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
				DRAWN BY IVY-LIN	DATE 2005/03/31	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)				
				CHECKED BY ALL IN	DATE 2005/03/31					
				APPROVED BY WWSCHANG	DATE 2005/03/31	MOLEX INCORPORATED DOCUMENT NO. SD-67643-003				
				MATERIAL NO. SEE TABLE				SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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